

Casting compound Wepuran VT 3406

The casting compound **Wepuran VT 3406** protects and insulates electronic components and assemblies against extreme climatic influence and aggressive media.

- Base: Polyurethane resin (UR)
- solids content > 99,2 %
- good flow characteristics
- highly elastic
- particularly suitable for sensitive electronic components since material tensions under thermal shocks are reduced
- operating temperature range **-65 to at least +90 °C [-85 to at least 194 °F]**
- for moderate requirements on optical properties, e.g. for encapsulating assemblies that must remain permanently visible
- good protection against shock, impact and vibration
- good resistance against water, moisture, lyes, acids and numerous chemicals
- easily removed for repair purposes

Characteristics

Colour/appearance		colourless, clear
Viscosity* at 20 °C [68 °F] DIN EN ISO 3219	Component A Hardener (component B) Mixture	900 ± 300 mPas 400 ± 100 mPas 1000 ± 300 mPas
Density at 20 °C [68 °F] DIN EN ISO 2811-1	Component A Hardener (component B) Mixture	0.94 ± 0.05 g/cm ³ 1.09 ± 0.05 g/cm ³ 0.96 ± 0.05 g/cm ³
Pot life of mixture at 19-21 °C [66.2-69.8 °F] in accordance with DIN EN 14022, approx. 200 mL)		
Double viscosity		≈ 15 min
Tenfold viscosity		≈ 25 min

* measured with Haake RS 600, C 35/1°, D = 100 s⁻¹,
viscosity measuring unit supplied by Thermo Fisher Scientific, www.thermofisher.com

Index: VT = Casting compound, clear

Physical and mechanical properties

These properties are reached after 14 days storage at room temperature (18–23 °C [64.4–73.4 °F]).

Property	Test method	Result
Shore-A hardness	ISO 48-4	15-25
Water absorption	DIN EN ISO 62 24 h/23 °C [73,4 °F] 30 min 100 °C [212 °F] , 15 min RT	≈ 0.2 % ≈ 0.5 %
Glass transition temperature Tg	TMA (Thermo mechanical analysis)	≈ -45 °C
Coefficient of thermal expansion CTE > Tg	TMA (Thermo mechanical analysis)	≈ 265 ppm/K
Thermal class*	based on DIN IEC 60 085	Y = 90 °C

* can be used in a temperature range of **-65 bis mind. +90 °C** [-85 up to at least 194 °F]. Both at the lower and upper ends of this range the performance and reliability of the material can be negatively affected in some applications. In these cases, additional pre-trials and tests are required.

Electrical properties

These properties are reached after 14 days storage at room temperature (18–23 °C [64.4–73.4 °F]).

Property	Test method	Result
Dielectric strength	IPC-TM-650, 2.5.6.1	≥ 54 kV/mm
Surface resistance	DIN EN 62631-3-2	≥ 3.5 x 10 ¹² Ohm
Specific volume resistivity	DIN EN 62 631-3-1	≥ 7.8 x 10 ¹¹ Ohm x cm
Comparative tracking index (CTI, tracking resistance)	DIN EN 60112	CTI > 600*

Processing



Please read this technical report and the publications listed below carefully before using the product. These sheets are enclosed with the first shipment of product or sample.

MSDS

The corresponding material safety data sheet contains detailed information and characteristics on safety precautions, environmental protection, transport, storage, handling and waste disposal.

TI

[Technical information TI 15/2](#) "Selection criteria and processing instructions for casting compounds"

TI

[Technical information TI 15/3](#) "Protective measures when using chemicals including lacquers, casting compounds, thinners, cleaning agents"

TI

[Technical information TI 15/10](#) "Processing of 2-pack systems"



Protect against humidity

Since the many different permutations make it impossible to evaluate the whole spectrum (parameters, reactions with materials used, chemical processes and machines) of processes and subsequent processes in all their variations, the parameters we recommend are to be viewed as guidelines only that were determined in laboratory conditions. We advise you to determine the exact process limitations within your production environment, in particular as regards compatibility with your specific follow-up processes, in order to ensure a stable fabrication process and products of the highest possible quality.

The specified product data is based upon standard processing conditions/test conditions of the mentioned norms and must be verified if necessary while observing suitable test conditions on processed products.

Feel free to contact our application technology department (ATD) if you have any questions or for a consultation.

Safety recommendation

- When using chemicals, the common precautions should be carefully noted.
- Ensure that extractor units of workplace ventilation arrangements are positioned at solvent source level.

Mixing



Component A : Hardener (Component B) = 4 : 1 (parts by weight)

On the labels of our containers, you will find the volume [L] and weight [kg]. The mixing ratio refers to the weight.

Auxiliary products recommended

- [ELPESPEC® sealing mastic EH 13.271](#)
solvent-free paste for sealing jobs in electronics and electrical engineering, self-adhesive and permelastastic
- [ELPESPEC® adhesion promoters EH 13.950/EH 13.951](#)
for improving the adhesion; **EH 13.950** is applied thinly to the parts that will come into contact with the casting compound while **EH 13.951** is mixed thoroughly with the casting compound prior to potting
- [ELPESPEC® mould release agent EH 13.650](#)
solvent-, silicone- and grease-free, for pre-treating the surfaces of parts to be potted; after curing, the potting can be easily removed from the mould without residue
- [ELPESPEC® accelerator B 4402](#)
reduces the curing time and the processing time, thus to be applied preferably with mixing and dosing units; stirred into component A prior to processing the casting compound
- [ELPESPEC® cleaning agent R 13.780](#)
for the cleaning of work place and tools; cleaning should be effected immediately after processing as cleaning becomes increasingly difficult the further the curing process progresses and is impossible after final curing

Drying/curing

The following specifications for a quantity of 25 g serve as a guideline:

	Room temperature (18–23 °C [64.4–73.4 °F])	125 °C [257 °F]
Tack-free	1 h	< 15 min
Final hardness	48 h	30 min

Curing at higher temperatures may lead to yellowing of the casting compound.

Packaging

The packing units available are indicated in our offer which we will send you upon request.

Shelf life and storage conditions



Shelf life: In sealed original containers at least 3 months



Storage conditions: +5 °C to +25 °C [+41 °F to +77 °F]



Protect against humidity



Protect against frost

For warehousing reasons, isolated cases may occur where the shelf life upon shipment is less than the shelf life indicated in this technical report. However, it is ensured that our products have **at least** two-thirds of their shelf life remaining when they leave our company. Labels on containers show shelf life and storage conditions.

Disclaimer

All descriptions and images of our goods and products contained in our technical literature, catalogues, flyers, circular letters, advertisements, price lists, websites, data sheets and brochures, and in particular the information given in this literature are non-binding unless expressly stated otherwise in the Agreement. This shall also include the property rights of third parties if applicable.

The products are exclusively intended for the applications indicated in the corresponding technical data sheets. The advisory service does not exempt you from performing your own assessments, in particular as regards their suitability for the applications intended. The application, use and processing of our products and of the products manufactured by you based on the advice given by our Application Technology Department are beyond our control and thus entirely your responsibility. The sale of our products is effected in accordance with our current terms of sale and delivery.

Any questions? We would be pleased to offer you advice and assistance in solving your problems. Samples and technical literature are available upon request.

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